



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32MP131DAE7	224R*501XXXY	A	9991	2025-04-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	500	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Not Applicable	NAC	SACN205	
Package designator	Package size	Number of instances	Shape	
BGA	14x14	289	Bulk solder	
Comment	Package : B0ED LFBGA 14X14 289L PITCH 0.8 MM DM00699792			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	224R*501XXXY		500.0000		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.220	mg	supplier	die	Silicon (Si)	7440-21-3		6.700	mg	927976	13399.97
				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	8033	116.00
				supplier	metallization	Copper (Cu)	7440-50-8		0.171	mg	23684	342.00
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	139	2.01
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4017	58.01
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	970	14.01
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	139	2.01
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5679	82.00
				supplier	Passivation	Silicon Oxide	7631-86-9		0.212	mg	29363	424.00
				supplier	Substrate	Copper (Cu)	7440-50-8		15.763	mg	110000	31526.88
Substrate (A29368)	Copper & its alloys	143.304	mg	supplier	Substrate	Nickel(Ni)	7440-02-0		10.031	mg	70000	20062.56
				supplier	Substrate	Gold (Au)	7440-57-5		0.573	mg	4000	1146.43
				supplier	Substrate	Thermosetting resin (Including filler)	Proprietary		3.009	mg	21000	6018.77
				supplier	Substrate	Glass cloth	65997-17-3		50.156	mg	350000	100312.80
				supplier	Substrate	Copper foil	7440-50-8		45.857	mg	320000	91714.56
				supplier	Substrate	Cured Resin	Proprietary		2.150	mg	15000	4299.12
				supplier	Substrate	Phthalocyanine blue	7727-43-7		4.299	mg	30000	8598.24
				supplier	Substrate	Silica	85954-11-6		4.299	mg	30000	8598.24
				supplier	Substrate	Barium sulfate	112-15-2		4.299	mg	30000	8598.24
				supplier	Substrate	Talc	64742-94-5		2.866	mg	20000	5732.16
Glue epoxy (2100AC)	Precious metals	3.890	mg	supplier	Glue or tape	Copper (Cu)	7440-50-8		3.307	mg	850000	6613.00
				supplier	Glue or tape	Silver (Ag)	7440-22-4		0.311	mg	80000	622.40
				supplier	Glue or tape	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9		0.152	mg	39000	303.42
				supplier	Glue or tape	2-[[2,2-bis[[[1-(oxallyloxy)methyl]butoxy)methyl]-	94108-97-1		0.117	mg	30000	233.40
				supplier	Glue or tape	tert-butyl peroxyneodecanoate	26748-41-4		0.004	mg	1000	7.78
Bonding wire (Cu)	Precious metals	2.158	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.084	mg	965500	4167.10
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.067	mg	31000	133.80
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.008	mg	3500	15.11
				supplier	Bonding wire	Silica(Fused)	60676-86-0		272.846	mg	950000	545691.40
Encapsulation (KE-G1250AAS)	Other inorganic materials	287.206	mg	supplier	Molding Compound	Epoxy resin	Proprietary		6.462	mg	22500	12924.27
				supplier	Molding Compound	Phenol resin	Proprietary		6.462	mg	22500	12924.27
				supplier	Molding Compound	Carbon Black	1333-86-4		1.436	mg	5000	2872.06
				supplier	Matte Sn	Tin (Sn)	7440-31-5		54.226	mg	964500	108452.24
Solderballs (SACN305)	Other Nonferrous metals & alloys	56.222	mg	supplier	Matte Sn	Silver (Ag)	7440-22-4		1.687	mg	30000	3373.32
				supplier	Matte Sn	Copper (Cu)	7440-50-8		0.281	mg	5000	562.22
				supplier	Matte Sn	Nickel (Ni)	7440-02-0		0.028	mg	500	56.22